Management Day at 45th Design Automation Conference Offers Design Managers Valuable Insights from Industry Peers

BOULDER, Colo. – May 5 2008 – The 45th Design Automation Conference (DAC) will feature a special Management Day session series on Tues. June 10. This fourth annual event will feature presentations from seven notable leaders of major fabless companies and independent device manufacturers (IDMs), including Intel, Qualcomm, Microsoft and ST Microelectronics. The speakers, whose collective experience touches on today’s most complex nanometer chips, will discuss the latest changes in design requirements and share some of their own trade-off analysis and decision criteria in dealing with issues such as the move to new technology nodes, optimizing for high-volume production, and addressing power constraints. DAC will be held June 8-13, 2008 at the Anaheim Convention Center in Anaheim, Calif. Details are available at www.dac.com.

“Participants in this year’s Management Day will have a unique opportunity to hear from their peers on the management decision criteria they used in some of their recent design projects,” said Limor Fix, general chair of the 45th DAC executive committee. “Yervant Zorian has done an excellent job of lining up a remarkable group of presenters for this year’s Management Day and I expect this event will provide participants with practical information they can apply in their own work.”

Management Day Agenda: Session 1 - 10:30 a.m. to 12:00 p.m.

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Managing Low Power SoC Development on Emerging Technology Nodes
Session Chair: Ron Wilson - EDN

- Key Design Challenges of 45nm Intel Atom Low Power Processor
  Elinora Yoeli, Vice President, Mobility Group, Intel Corp.

- 45/40nm Low-Power Design Solutions for Wireless Multi-Media SoCs
  Philippe Magarshack, Vice President, Central R&D, ST Microelectronics, France

- Challenges that new wireless SOC designs are facing from new process technology nodes
  Charles Matar, Vice President of Engineering, Qualcomm

Session 2 - 2:00 p.m. to 4:00 p.m.
Trade-offs and Choices for Advanced SoCs in High-volume Application
Session Chair: Nic Mokhoff - EE Times

- A Case Study of 65nm 5-Million Instances Chip Development
  Andrew C. Chang, Vice President Design Technology, MediaTek, Taiwan

- A 45nm Power Optimized Digital Baseband SoC - An Introspective Review
  Bob Pitts, 45nm Platform Manager, Texas Instruments

- Graphics Processor for XBOX-360 - Cost Reduction - Design Challenges and Decision Criteria
  Srinivas Nori, ASIC Design Manager, XBOX Silicon Development, Microsoft Corp.

- From Specifications to High Volume Production
  Manuel D'Abreu, Director, SanDisk Corp.

Session 3 - 4:30 p.m. to 5:30 p.m.
Making Critical Decisions for Emerging SoC Development
Session Chair: Peggy Aycinena - EDA Confidential

- This panel session will include the speakers from the first two sessions and provide the audience an opportunity to communicate directly with the speakers and receive responses to their questions

The Management Day sessions are scheduled for Tues. June 10, 2008 from 10:30 a.m. to 6:00 p.m. The registration fee of $95.00 includes handout materials, refreshment breaks and the closing reception.
Registration

To register for DAC visit www.dac.com or call 1-800-321-4573 in the U.S. to request registration materials. The advance conference registration discount deadline is May 19, 2008.

About DAC

The Design Automation Conference (DAC) is recognized as the premier event for the design of electronic circuits and systems, and for Electronic Design Automation (EDA) and silicon solutions. A diverse worldwide community representing more than 1,500 organizations attends each year, from system designers and architects, logic and circuit designers, validation engineers, CAD managers, senior managers and executives to researchers and academicians from leading universities. Close to 60 technical sessions selected by a committee of electronic design experts offer information on recent developments and trends, management practices and new products, methodologies and technologies. A highlight is its Exhibition and Suite area with approximately 250 of the leading and emerging EDA, silicon and IP providers. The conference is sponsored by the Association for Computing Machinery’s Special Interest Group on Design Automation (ACM/SIGDA), the Circuits and Systems Society and Council on Electronic Design Automation of the Institute of Electrical and Electronics Engineers (IEEE/CASS/CEDA) and the Electronic Design Automation Consortium (EDA Consortium). More details are available at: www.dac.com.